



# Press Release

## **UNISEM RECORDED RM329.3 MILLION REVENUE, RM41.3 MILLION IN NET INCOME IN 1Q 2010**

**Kuala Lumpur, 5 May 2010** – Unisem (M) Berhad today announced results for the first quarter ended 31 March 2010 (**1Q10**).

The Group recorded revenue of RM329.3 million for 1Q10, a 82.2% growth from the same quarter a year ago (**1Q09**). For the current quarter the Group achieved net profit of RM41.3 million compared to net loss of RM23.4 million in the same quarter in 2009 (**1Q09**). The significant increase in revenue and improvement in the net profit was mainly due to increase in overall sales volume as a result of recovery in the semiconductor industry.

Group profit before taxation (**PBT**) came in at RM45.8 million, an increase of 25.4% from RM36.5 million in the prior quarter (**4Q09**). The improvement in PBT was mainly due to increase in overall sales.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 1Q10 was RM87.7 million, an increase of 7.5% from RM81.6 million in 4Q09. EBITDA margin in 1Q10 also improved to 27% from 26% in 4Q09.

Equipment capacity utilization averaged at about 74% for the group in 1Q10. Group capital expenditure incurred in 1Q10 was about RM61.9 million, principally for purchase of assembly and final test equipment for Unisem Chengdu and Unisem (M) Berhad.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "The Group saw a strong first quarter performance in its business as opposed to a normally subdued first quarter following a seasonally strong fourth quarter. The board of directors expects the demand for the Group's products and services to improve further in the second quarter and the business of the Group for the remaining period to the end of the financial year to remain strong."

### **About Unisem**

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at [www.unisemgroup.com](http://www.unisemgroup.com).